multicomp PRO

RoHS

Features

- · Reflow Solderable
- · High Luminous Intensity and Low Power Dissipation
- · Good Reliability and Long Life
- Lead Free

Applications

- Optical indicator
- Indoor display
- · Backlighting in dashboard and switch
- · Flat backlighting for LCD, symbol and display
- General use

Compliant

Specifications

Dice material : AlGaInP

Emmiting Colour : Blue

Lens colour : Water Clear

Dominant wavelength : 475nm

Luminous intensity @ 5mA : 60mcd

Luminous intensity @ 20mA : 200mcd

Selection Guide

Part Number	Chip materials	Lens Type	Luminou	Viewing Angle		
			Min	Тур	Max	2θ1/2
MP008284	Blue (AlGalnP)	Water Clear	35	60	-	120
			Luminous intensity (mcd) @ 20mA Viewing Angle			
			Min	Тур	Max	2θ1/2
			100	200	-120	

Electrical and Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Тур	Max	Units	Test conditions
Converd voltage	VF	2.5	-	3.1	V	IF=5mA
Forward voltage		2.8	-	3.4		IF=20mA
Reverse Current	IR	-	-	10	uA	VR=5V
Danein and wavelenath	λd	465	-	475	nm	IF=5mA
Dominant wavelength		465	-	475		IF=20mA

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Units	
Power Dissipation	Pd	68	mW	
DC Forward Current	IF	20	mA	
Peak Forward Current [1]	IFP	100	mA	
Reverse Voltage	VR	5	V	
Electrostatic Discharge (HBM)	ESD	2000	V	
Operating Temperature	Topr	-40 to +85	°C	
Storage Temperature	Tstg	-40 to +100	°C	

Notes:

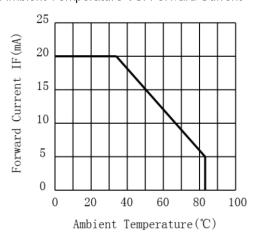
- 1. 1/10 Duty cycle,0.1ms pulse width
- 2. The above forward voltage measurement allowance tolerance ±0.1V
- 3. The tolerance of wave length:±1nm

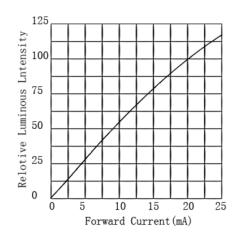


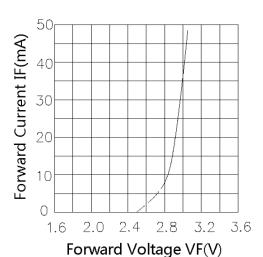
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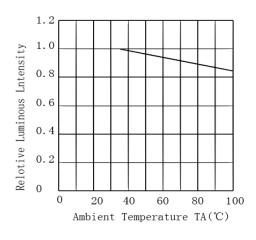
Typical optical characteristics curves

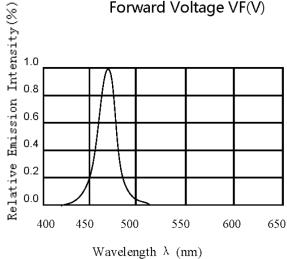
Ambient Temperature VS. Forward Current

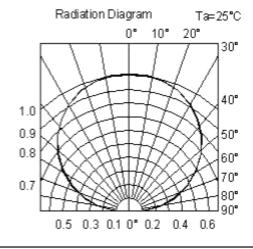








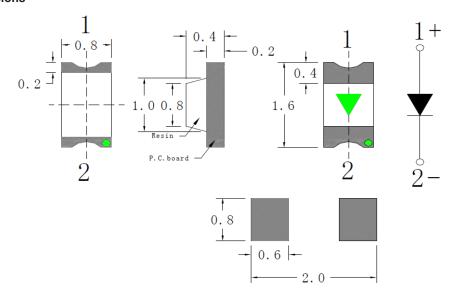






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Dimensions



Notes Dimensions : Millimetres

- 1. All dimension tolerance is ±0.2mm unless otherwise noted
- 2. All PCB and markings are subject to change without prior notice
- 3. Polarity mark: ▼or T

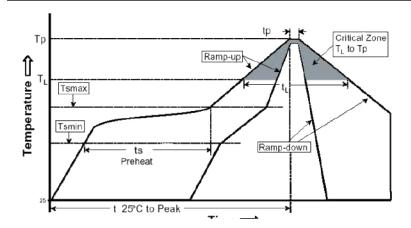
SMT Reflow Soldering Instructions

- 1. High temperature welding recommended no more than 2 times
- 2. When soldering, do not put stress on the LEDs during heating
- 3. Reflow temperature distribution (Acc.to J-STD-020D)

Profile feature	Sn-Pb Eutec	tic Assembly	Pb-Free Assembly		
Profile leature	Large body	Small body	Large body	Small body	
Average ramp-up rate (TL to Tp)		3°C / sec	econd max.		
Preheat -Temperature Min (TSmin) -Temperature Max (TSmax) -Time (min to max) (ts)	100°C 150°C 60 to 120 seconds		150°C 200°C 60 to 180 seconds		
Tsmax to TL -Ramp-up Rate			3°C / sec	cond max.	
Time maintained above -Temperature (TL) -Time (tL)	183°C 60 to 150 seconds		217°C 60 to 150 seconds		
Peak Temperature (Tp)	225 +0/-5°C	240 +0/-5°C	245 +0/-5°C	260 +0/-5°C	
Time within 5°C of actual Peak Temperature (tp)	10 to 30 seconds		10 to 30 seconds	20 to 40 seconds	
Ramp-down Rate	6°C / second max.				
Time 25°C to Peak Temperature 6 minutes max.		8 minutes max.			







Soldering iron

- 1. When hand soldering, the temperature of the iron must be less than 350°C for 3 seconds
- 2. The hand solder should be done only once

Part Number Table

Description	Part Number
Chip LED, Blue, 475nm, 120°, -120mcd, Surface Mount	MP008284

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